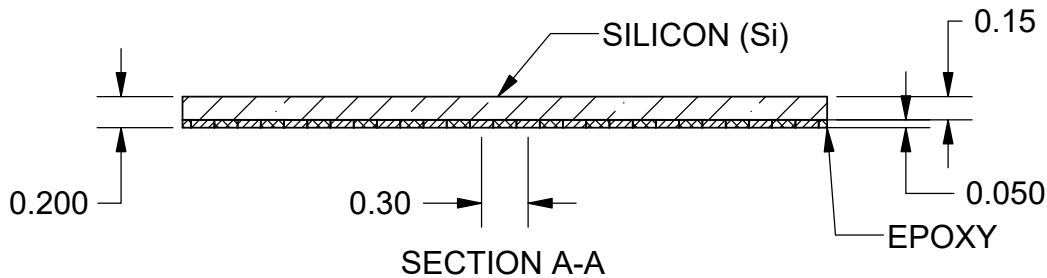
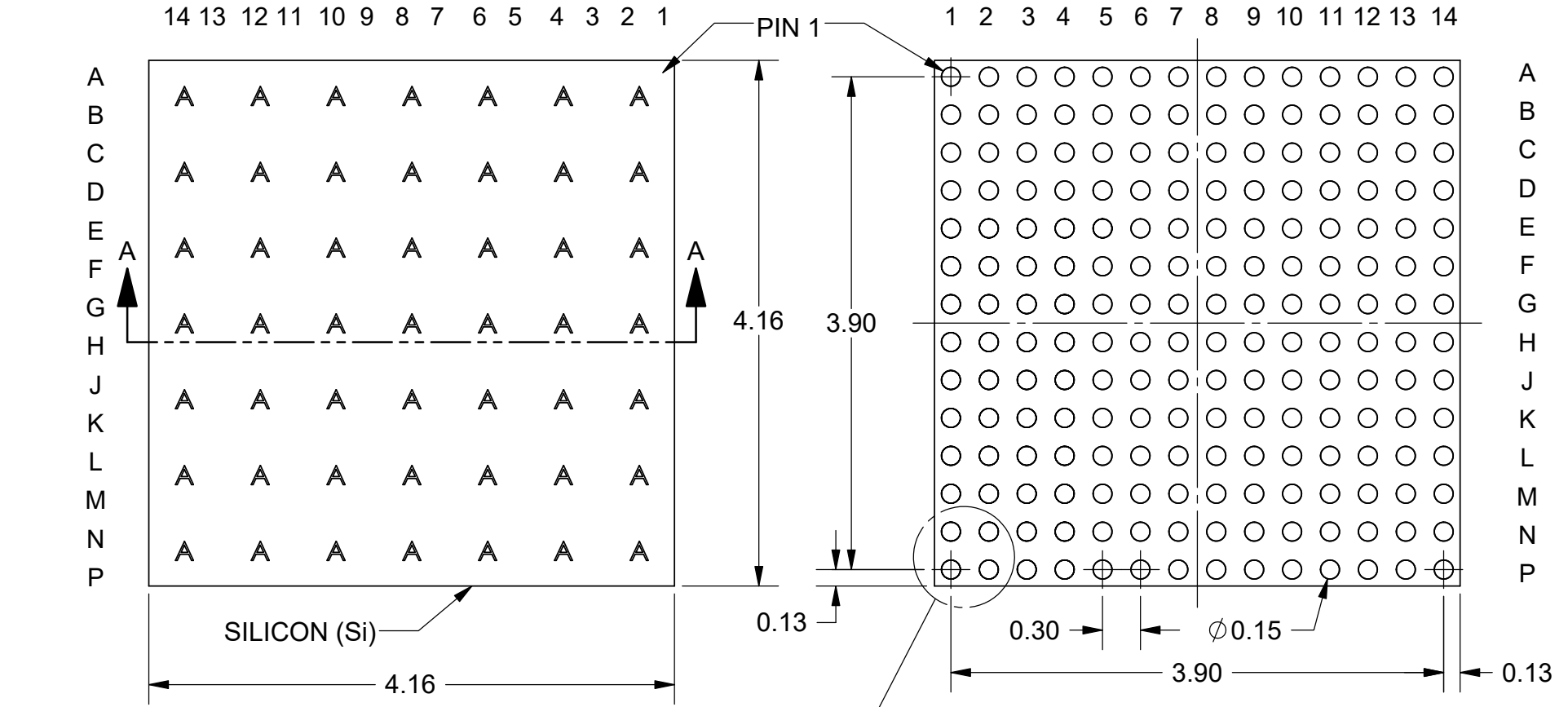


TOP VIEW

PAD VIEW



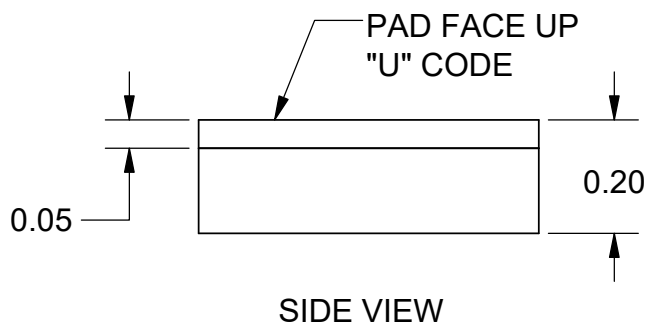
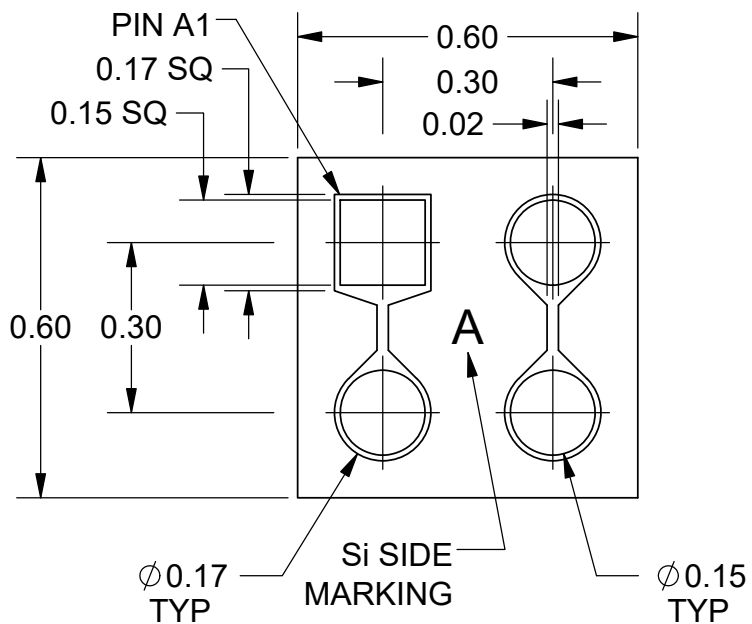
SEE DETAIL "B"
PAGE 2

- Notes: (Unless Otherwise Specified).
 1) ALL DIMENSIONS ARE IN MM.
 2) PAD ALLOY: Cu (50 μm THICK).
 3) PAD Cu DIAMETER 0.15mm.
 4) DIE MATERIAL: Si (SILICON).
 5) DAISY CHAIN PATTERN (SEE PAGE 3).
 6) PART NUMBER SYSTEM (SEE PAGE 4/5).

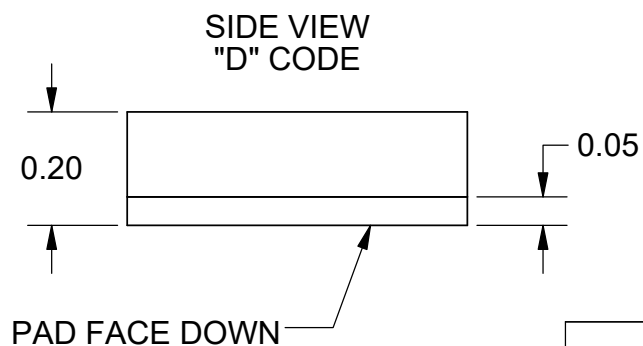
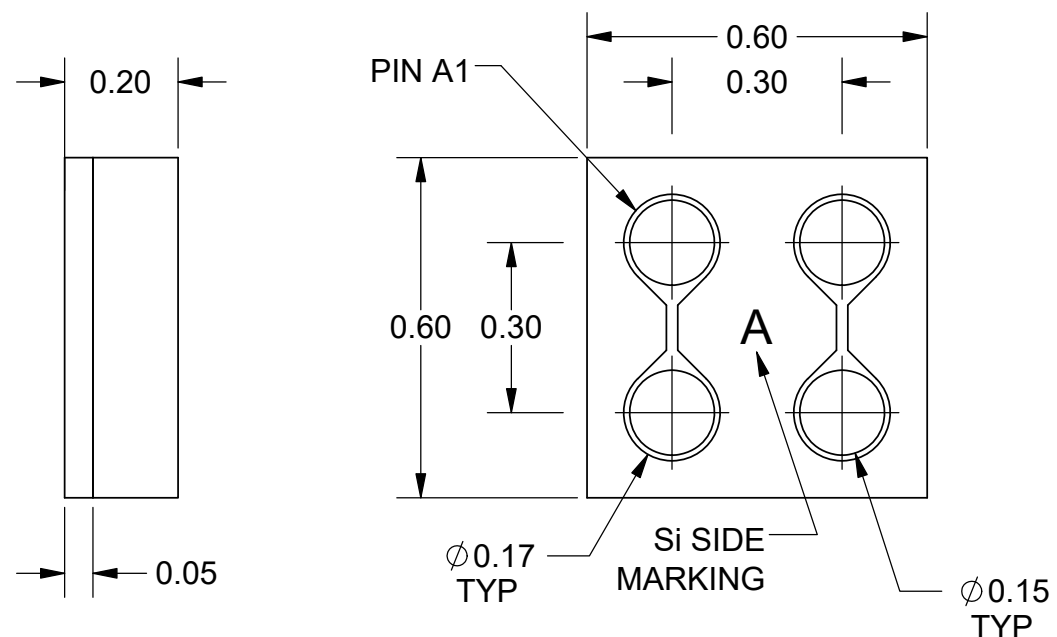
TOLERANCE UNLESS NOTED		APPROVALS		DATE						
X.X	+/- 0.3	DRAWN J. Hines		3/24/2017						
X.XX	+/- 0.03	ENG M. Hart		3/24/2017		TITLE eWLP196T.3-DC148D				
X.XXX	+/- 0.003	MFG				196L P=0.3mm				
ALL DIMENSIONS IN		QA		SCALE 20.5:1		SIZE A		DRAWING NO. 631480		REV B
<input type="checkbox"/> INCHES <input checked="" type="checkbox"/> MILLIMETERS		CUST								
THIRD ANGLE PROJECTION		REVISED								

DETAIL B
COPPER POST
SQUARE AND ROUND
PRIOR TO DICING

OPTION SQ
SQUARE POST



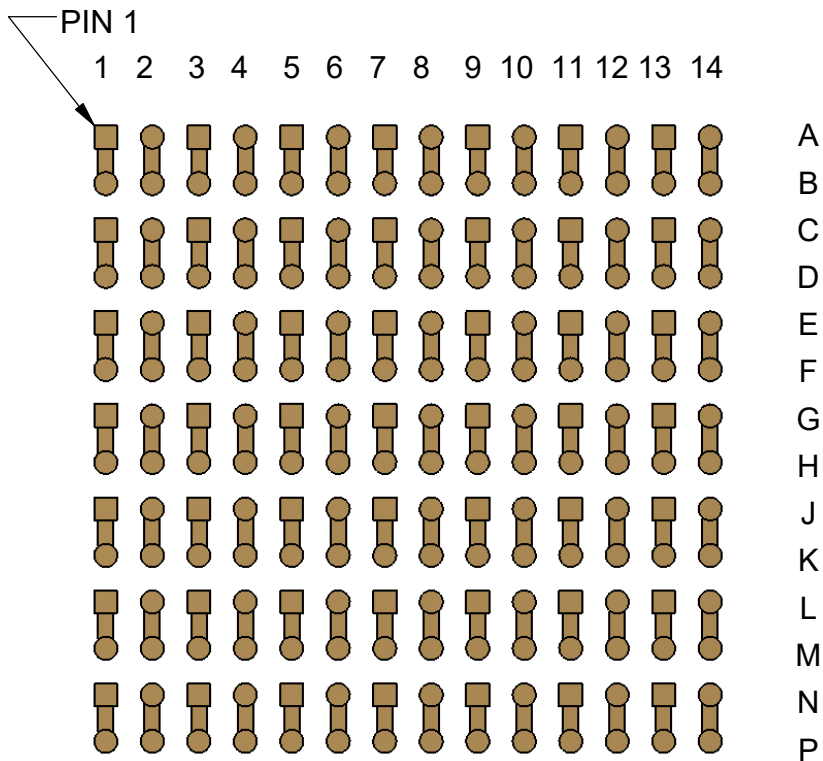
OPTION STANDARD
ROUND POST



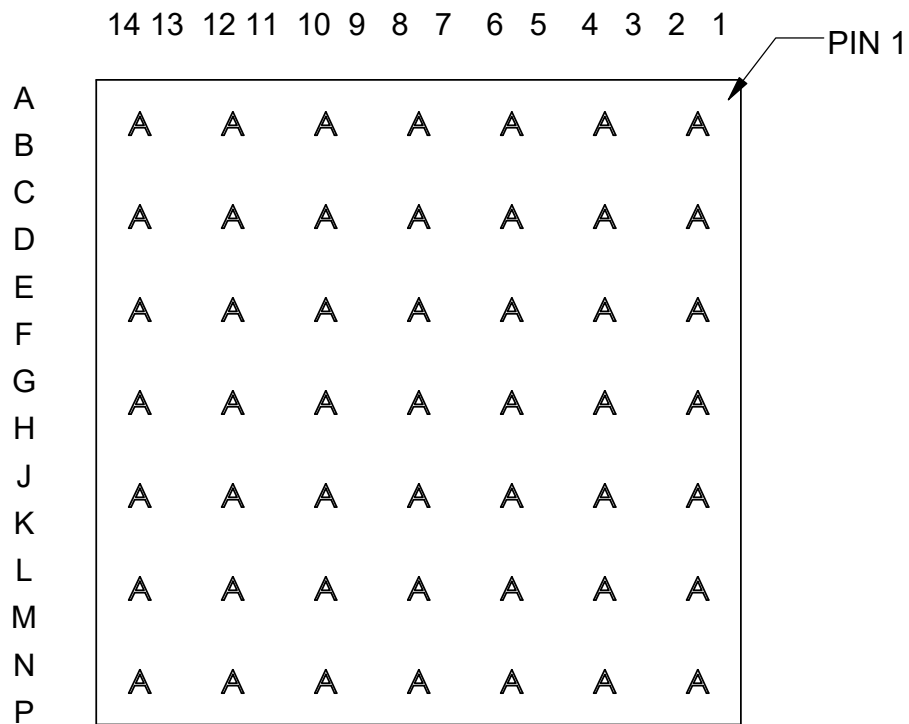
TopLine [®]			
TITLE eWLP196T.3-DC148D 196L P=0.3mm			
SCALE 75:1	SIZE A	DRAWING NO. 631480	REV B
DO NOT SCALE DRAWING			SHEET 2 OF 9

DAISY CHAIN PATTERN SHOWN WITH SQUARE PADS

PAD VIEW



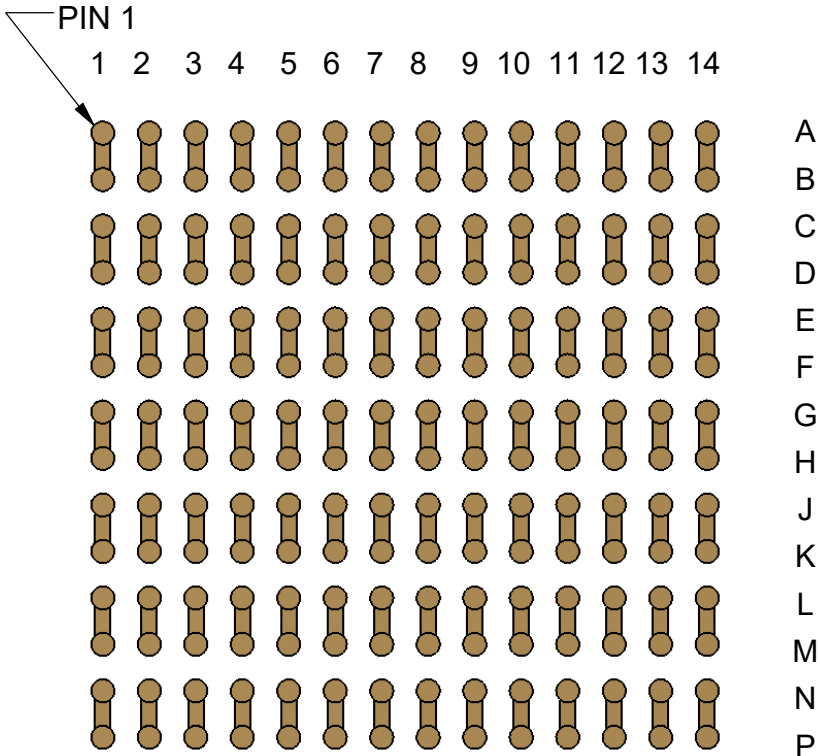
SILICON Si VIEW



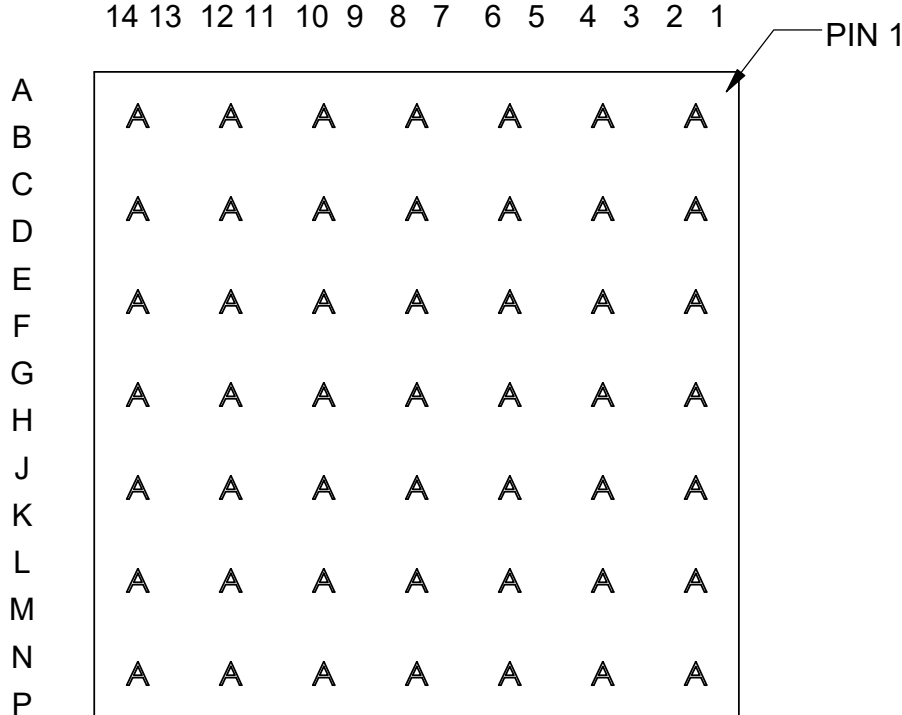
TopLine [®]			
TITLE eWLP196T.3-DC148D 196L P=0.3mm			
SCALE 20.5:1	SIZE A	DRAWING NO. 631480	REV B
DO NOT SCALE DRAWING			SHEET 3 OF 9

DAISY CHAIN PATTERN
SHOWN WITH ROUND PADS

PAD VIEW

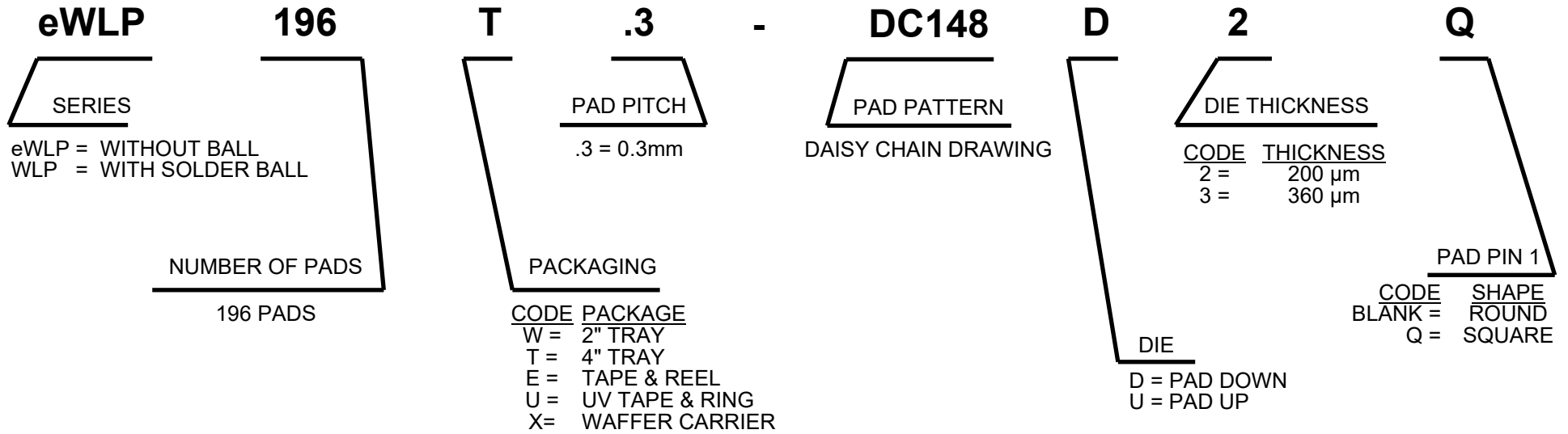


SILICON Si VIEW



TopLine®			
TITLE eWLP196T.3-DC148D 196L P=0.3mm			
SCALE 20.5:1	SIZE A	DRAWING NO. 631480	REV B
DO NOT SCALE DRAWING			SHEET 4 OF 9

PART NUMBERING SYSTEM




TopLine [®]			
TITLE eWLP196T.3-DC148D 196L P=0.3mm			
SCALE 20.5:1	SIZE A	DRAWING NO. 631480	REV B
DO NOT SCALE DRAWING			SHEET 5 OF 9

PART NUMBER TABLE

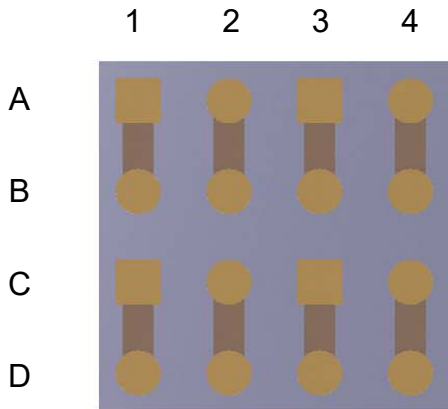
DWG	PART NUMBER	DIE THICKNESS	PAD PIN 1	PAD UP/DOWN	PACKAGING
SQUARE PIN 1 PAD					
131487	eWLP196W.3-DC148U2Q	200 µm	SQ	UP	2-INCH TRAY
131488	eWLP196W.3-DC148D2Q	200 µm	SQ	DOWN	2-INCH TRAY
131489	eWLP196T.3-DC148U2Q	200 µm	SQ	UP	4-INCH TRAY
131480	eWLP196T.3-DC148D2Q	200 µm	SQ	DOWN	4-INCH TRAY
131481	eWLP196E.3-DC148D2Q	200 µm	SQ	DOWN	TAPE & REEL
131482	eWLP196E.3-DC148D2Q	200 µm	SQ	DOWN	CUT TAPE
131483	eWLP196U.3-DC148U2Q	200 µm	SQ	UP	SAWN WAFER - UV TAPE & RING
131485	eWLP196X.3-DC148U2Q	200 µm	SQ	UP	UNSAWN WAFER

DWG	PART NUMBER	DIE THICKNESS	PAD PIN 1	PAD UP/DOWN	PACKAGING
ROUND PIN 1 PAD					
631487	eWLP196W.3-DC148U2	200 µm	ROUND	UP	2-INCH TRAY
631488	eWLP196W.3-DC148D2	200 µm	ROUND	DOWN	2-INCH TRAY
631489	eWLP196T.3-DC148U2	200 µm	ROUND	UP	4-INCH TRAY
631480	eWLP196T.3-DC148D2	200 µm	ROUND	DOWN	4-INCH TRAY
631481	eWLP196E.3-DC148D2	200 µm	ROUND	DOWN	TAPE & REEL
631482	eWLP196E.3-DC148D2	200 µm	ROUND	DOWN	CUT TAPE
631483	eWLP196U.3-DC148U2	200 µm	ROUND	UP	SAWN WAFER - UV TAPE & RING
631485	eWLP196X.3-DC148U2	200 µm	ROUND	UP	UNSAWN WAFER

DWG	PART NUMBER	DIE THICKNESS	PAD PIN 1	PAD UP/DOWN	PACKAGING
ROUND PIN 1 PAD					
731487	eWLP196W.3-DC148U3	360 µm	ROUND	UP	2-INCH TRAY
731488	eWLP196W.3-DC148D3	360 µm	ROUND	DOWN	2-INCH TRAY
731489	eWLP196T.3-DC148U3	360 µm	ROUND	UP	4-INCH TRAY
731480	eWLP196T.3-DC148D3	360 µm	ROUND	DOWN	4-INCH TRAY
731481	eWLP196E.3-DC148D3	360 µm	ROUND	DOWN	TAPE & REEL
731482	eWLP196E.3-DC148D3	360 µm	ROUND	DOWN	CUT TAPE
731483	eWLP196U.3-DC148U3	360 µm	ROUND	UP	SAWN WAFER - UV TAPE & RING
731485	eWLP196X.3-DC148U3	360 µm	ROUND	UP	UNSAWN WAFER

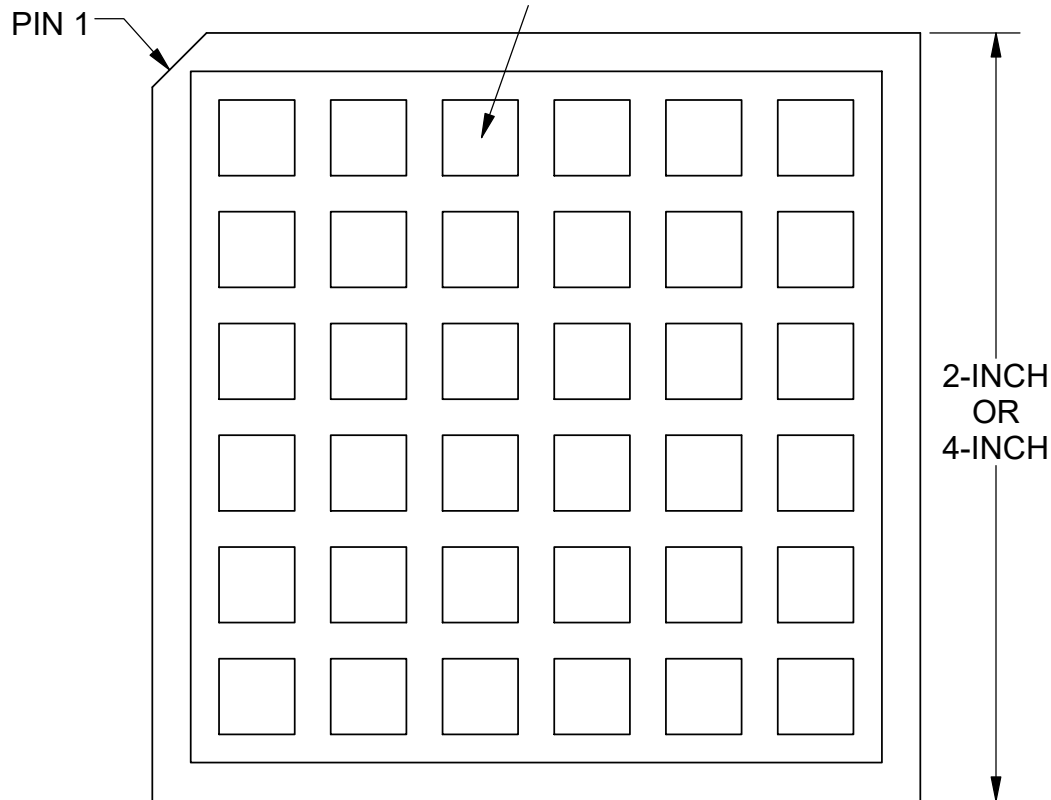
			
TITLE		eWLP196T.3-DC148D 196L P=0.3mm	
SCALE	SIZE	DRAWING NO.	REV
20.5:1	A	631480	B
DO NOT SCALE DRAWING			SHEET 6 OF 9

SQ PAD UPPER LEFT
DAISY CHAIN SIMULATION
SCALE= 40:1



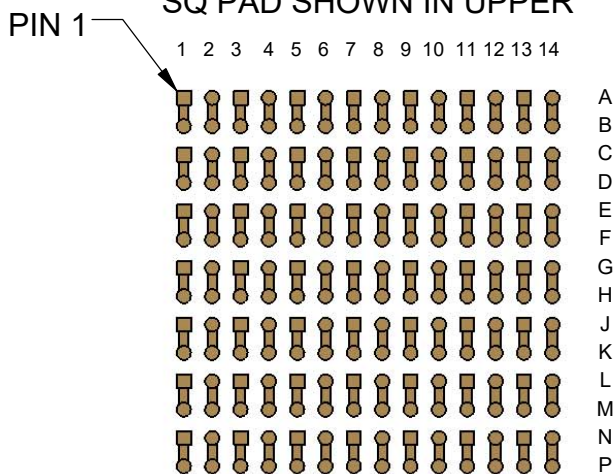
PAD SIDE UP ORIENTATION
WAFFLE PACK

TYPICAL WAFFLE PACK
IC CHIP TRAY
SCALE = 2:1



NUMBER OF POCKETS WILL CHANGE
BASED ON THE SIZE OF THE WLP CHIP

DAISY CHAIN WITH
SQ PAD SHOWN IN UPPER



Notes: (Unless Otherwise Specified).

- 1) EXAMPLE OF TOP SIDE LASER MARKING.
- 2) ORIENT LETTERS FOR LOCATION OF PIN A1 CORNER.
- 3) ALLOWABLE LETTER MARKING: A, F, T, M, L, Y, AND P.
- 4) SINGLE LETTER IS REPEATED MULTIPLE TIMES ACROSS TOP SIDE.
- 5) DAISY CHAIN IS HIDDEN UNDER RESIN ON BALL SIZE.
- 6) TOP SIDE DOES NOT HAVE A DOT FOR LOCATION OF PIN A1.
- 7) LETTERS ARE NOT MARKED ON BOTTOM (BALL) SIDE.

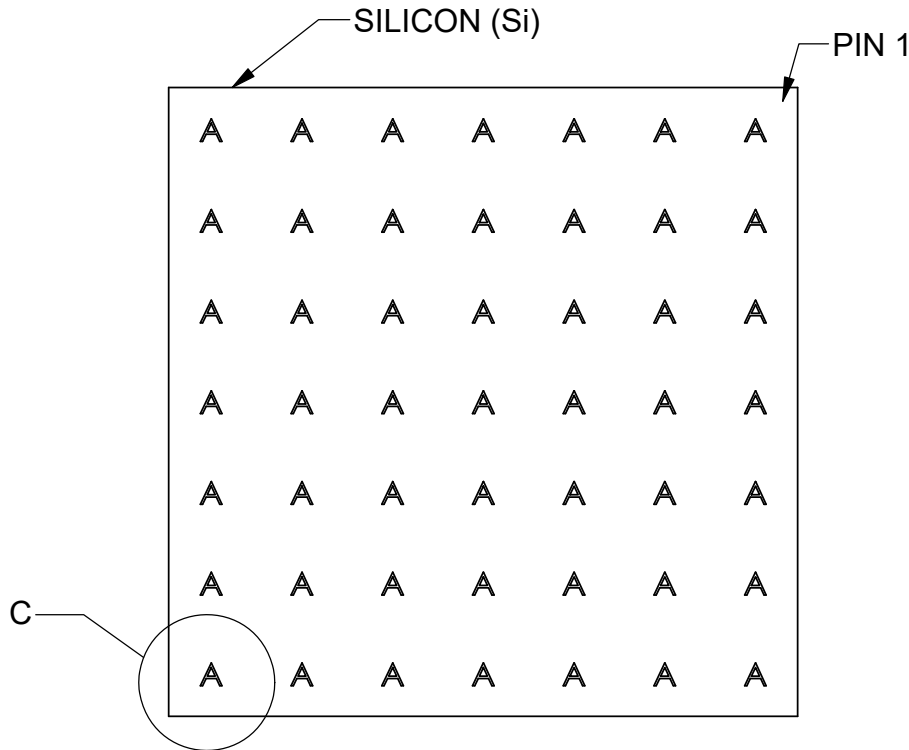
MARKING CODE	
PITCH	LETTER
0.3MM	A
0.4MM	F
0.5MM	P

TopLine [®]			
TITLE		eWLP196T.3-DC148D 196L P=0.3mm	
SCALE	SIZE	DRAWING NO.	REV
12.5:1	A	631480	B
DO NOT SCALE DRAWING			SHEET 7 OF 9

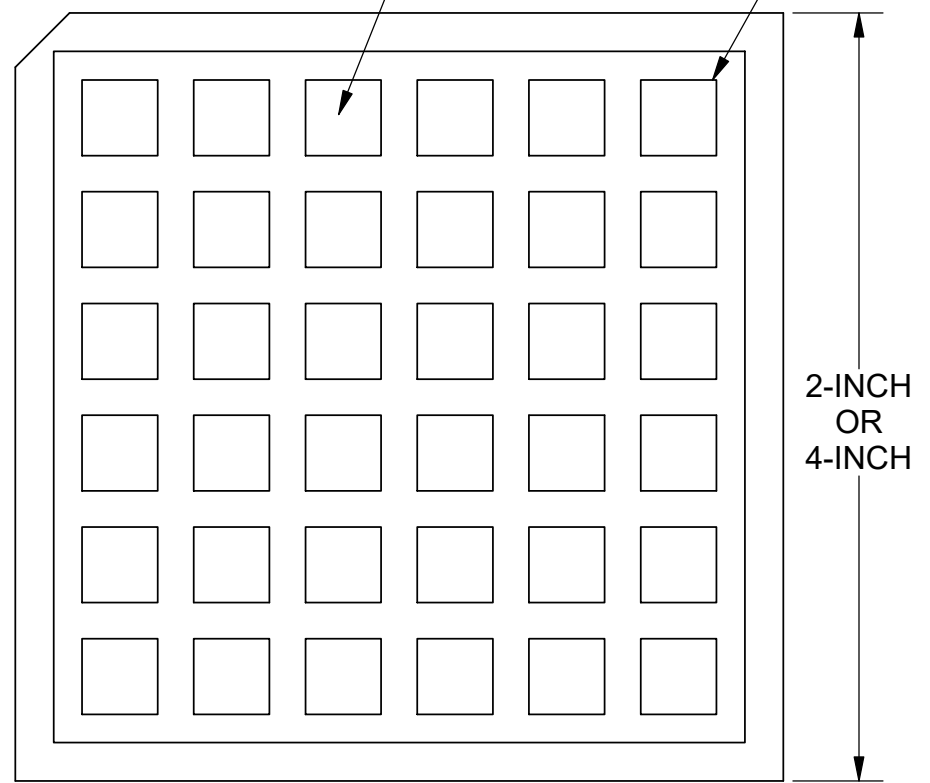
TOP VIEW

PAD SIDE DOWN ORIENTATION
WAFFLE PACK

TYPICAL WAFFLE PACK
IC CHIP TRAY
SCALE = 2:1

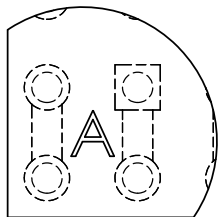


EXAMPLE ORIENTATION
OF MARKINGS ON eWLP

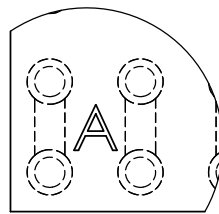


NUMBER OF POCKETS WILL CHANGE
BASED ON THE SIZE OF THE WLP CHIP

DAISY CHAIN VIEWED THRU DIE



DAISY CHAIN
ORIENTATION
DETAIL C
SCALE 40 : 1
SQUARE PAD



DAISY CHAIN
ORIENTATION
DETAIL C
SCALE 40 : 1
ROUND PAD

Notes: (Unless Otherwise Specified).

- 1) EXAMPLE OF TOP SIDE LASER MARKING.
- 2) ORIENT LETTERS FOR LOCATION OF PIN A1 CORNER.
- 3) ALLOWABLE LETTER MARKING: A, F, T, M, L, Y, AND P.
- 4) SINGLE LETTER IS REPEATED MULTIPLE TIMES ACROSS TOP SIDE.
- 5) DAISY CHAIN IS HIDDEN UNDER RESIN ON BALL SIZE.
- 6) TOP SIDE DOES NOT HAVE A DOT FOR LOCATION OF PIN A1.
- 7) LETTERS ARE NOT MARKED ON BOTTOM (BALL) SIDE.

MARKING CODE	
PITCH	LETTER
0.3MM	A
0.4MM	F
0.5MM	P

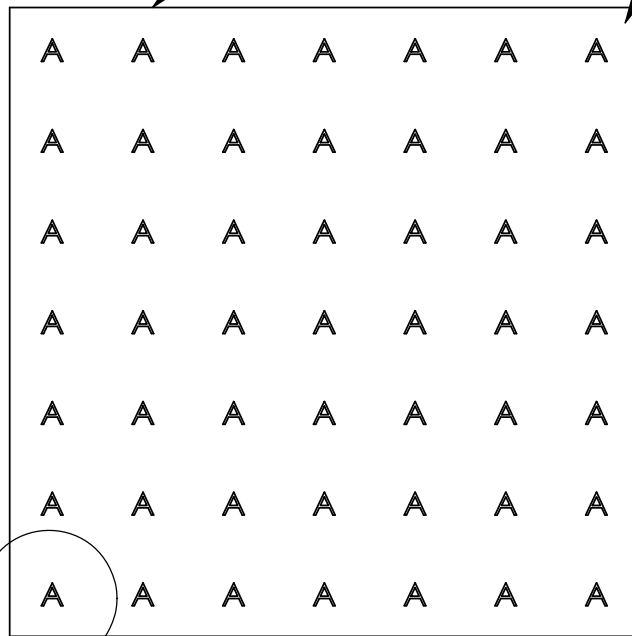
TopLine [®]			
TITLE		eWLP196T.3-DC148D	
		196L P=0.3mm	
SCALE	SIZE	DRAWING NO.	REV
20:1	A	631480	B
DO NOT SCALE DRAWING			SHEET 8 OF 9

eWLP ORIENTATION
TAPE AND REEL

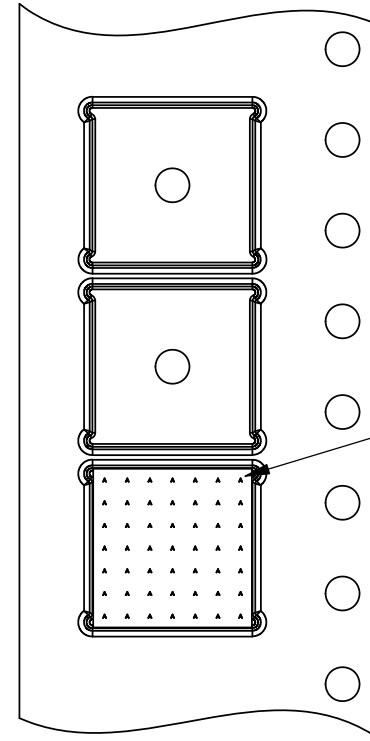
TOP VIEW

SILICON (Si)

PIN 1



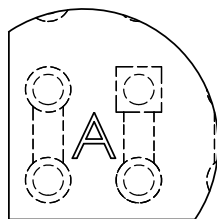
EXAMPLE ORIENTATION
OF MARKINGS ON eWLP



PIN 1

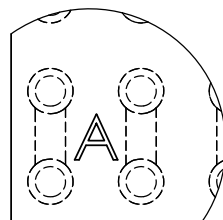
DIRECTION OF FEED

DAISY CHAIN VIEWED THRU DIE



DAISY CHAIN
ORIENTATION

DETAIL D
SCALE 40 : 1
SQUARE PAD



DAISY CHAIN
ORIENTATION

DETAIL D
SCALE 40 : 1
ROUND PAD

Notes: (Unless Otherwise Specified).

- 1) EXAMPLE OF TOP SIDE LASER MARKING.
- 2) ORIENT LETTERS FOR LOCATION OF PIN A1 CORNER.
- 3) ALLOWABLE LETTER MARKING: A, F, T, M, L, Y, AND P.
- 4) SINGLE LETTER IS REPEATED MULTIPLE TIMES ACROSS TOP SIDE.
- 5) DAISY CHAIN IS HIDDEN UNDER RESIN ON PAD SIZE.
- 6) TOP SIDE DOES NOT HAVE A DOT FOR LOCATION OF PIN A1.
- 7) LETTERS ARE NOT MARKED ON BOTTOM PAD SIDE.

MARKING CODE	
PITCH	LETTER
0.3MM	A
0.4MM	F
0.5MM	P

TopLine[®]

TITLE eWLP196T.3-DC148D			
196L P=0.3mm			
SCALE 20:1	SIZE A	DRAWING NO. 631480	REV B
DO NOT SCALE DRAWING			SHEET 9 OF 9